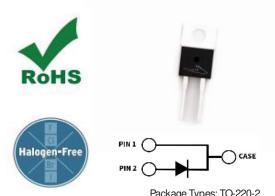


#### 3rd Generation 600 V, 2 A Silicon Carbide Schottky Diode

#### **Description**

With the performance advantages of a Silicon Carbide (SiC) Schottky Barrier diode, power electronics systems can expect to meet higher e iciency standards than Si-based solutions, while also reaching higher frequencies and power densities. SiC diodes can be easily paralleled to meet various application demands, without concern of thermal runaway. In combination with the reduced cooling requirements and improved thermal performance of SiC products, SiC diodes are able to provide lower overall system costs in a variety of diverse applications.



#### Package Types: TO-220-2 Marking: C3D02060A

#### **Features**

- ullet Low Forward Voltage  $(V_F)$  Drop with Positive Temperature Coe icient
- Zero Reverse Recovery Current / Forward Recovery Voltage
- Temperature-Independent Switching Behavior

#### **Applications**

- Industrial Switched Mode Power Supplies
- Uninterruptible & AUX Power Supplies
- Boost for PFC & DC-DC Stages
- Solar Inverters

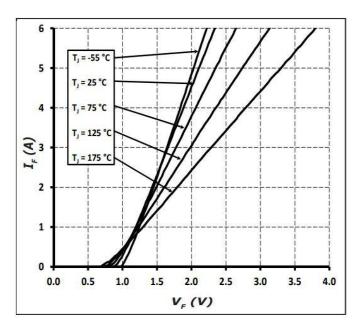
## **Maximum Ratings** ( $T_C = 25^{\circ}C$ Unless Otherwise Specified)

Parameter	Symbol	Value	Unit	Test Conditions	Notes	
Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	600	V			
DC Blocking Voltage	V <sub>DC</sub>	600	V			
		8		T <sub>J</sub> = 25 °C		
Continuous Forward Current	I <sub>F</sub>	4		T <sub>J</sub> = 135 °C	Fig. 3	
		2	A	T <sub>J</sub> = 161 °C		
Repetitive Peak Forward Surge Current	  FRM	11		$T_{\rm C} = 25  {\rm ^{\circ}C}$ , $t_{\rm p} = 10  {\rm ms}$ , Half Sine Wave		
		7.5		$T_{\rm C} = 110$ °C, $t_{\rm p} = 10$ ms, Half Sine Wave		
Non-Repetitive Forward Surge Current	I <sub>FSM</sub>	16.5		$T_{\rm C} = 25  {\rm ^{\circ}C}$ , $t_{\rm p} = 10  {\rm ms}$ , Half Sine Wave	F - 0	
		15		$T_{\rm C} = 110 {\rm ^{\circ}C}$ , $t_{\rm p} = 10 {\rm ms}$ , Half Sine Wave	Fig. 8	
Non-Repetitive Peak Forward Surge Current	 F,Max	120		$T_{\rm C} = 25 {\rm ^{\circ}C}, t_{\rm p} = 10 \mu \rm s,  Pulse$		
		110		T <sub>C</sub> = 110°C, t <sub>p</sub> = 10 μs, Pulse		
Power Dissipation	P <sub>tot</sub>	39.5	W	T <sub>J</sub> = 25 °C	Fig. 4	
		17		T <sub>J</sub> = 110 °C		
i²t value	i²dt	1.35	A²s	$T_c = 25 ^{\circ}\text{C},  t_p = 10 \text{ms}$		
		1.12		$T_{c} = 110 ^{\circ}\text{C}, t_{p} = 10 \text{ms}$		

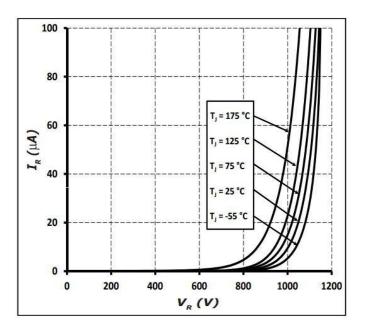
### **Electrical Characteristics**

Parameter	Symbol	Тур.	Max.	Unit	Test Conditions	Notes
Forward Voltage	.,	1.5	1.7	V	I <sub>F</sub> = 2 A, T <sub>i</sub> = 25 °C	
	V <sub>F</sub>	1.8	2.4		I <sub>F</sub> = 2 A, T <sub>j</sub> = 175 °C	Fig. 1
Reverse Current		3	15		$V_R = 600 \text{ V}, T_j = 25 \text{ °C}$	
	l <sub>R</sub>	6	55	μΑ	V <sub>R</sub> = 600 V, T <sub>j</sub> = 175 °C	Fig. 2
Total Capacitive Charge	Q <sub>c</sub>	5.8		nC	$V_R = 400 \text{ V}, T_j = 25 \text{ °C}$	Fig. 5
		175			$V_R = 0 \text{ V}, T_j = 25 ^{\circ}\text{C}, f = 1 \text{ MHzj} =$	25 °C, f = 1 MHzC
Total Capacitance	С			pF		

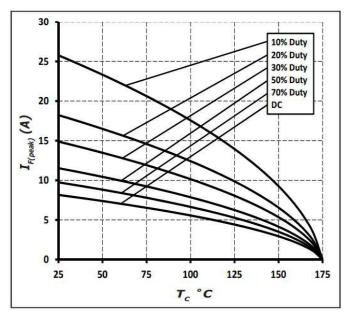
### **Typical Performance**



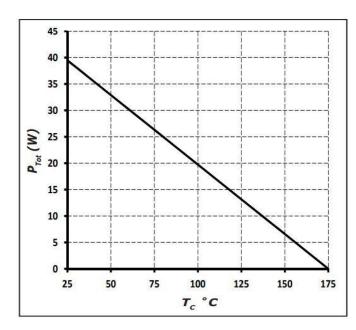
**Figure 1**Forward Characteristics



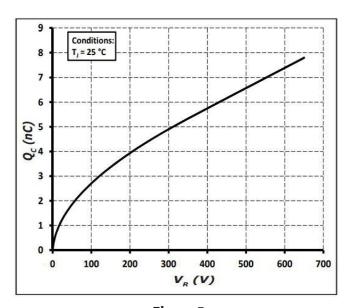
**Figure 2**Reverse Characteristics



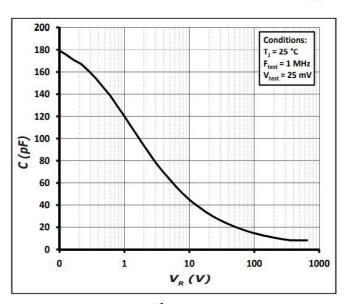
**Figure 3**Current Derating



**Figure 4**Power Derating



**Figure 5**Total Capacitance vs. Reverse Voltage



**Figure 6**Capacitace vs. Reverse Voltage

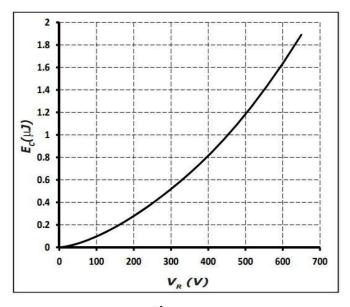
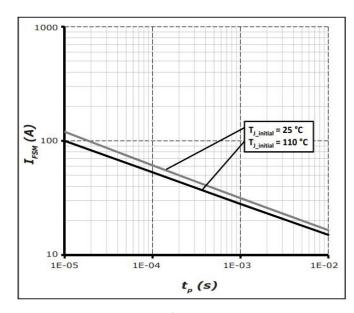


Figure 7
Capacitance Stored Energy



**Figure 8**Non-Pepetitive Peak Forward Surge Current versus Pulse Duration (sinusoidal waveform)

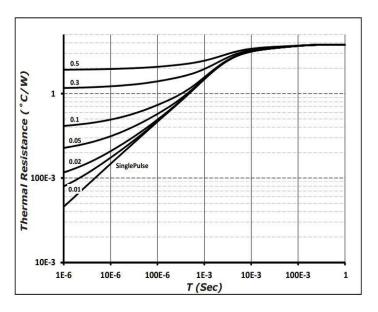


Figure 9
Transient Thermal Impedance

### **Diode Model**

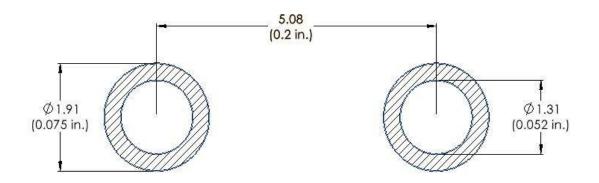
$$Vf_T = V_T + If^*R_T$$

$$V_{T=} 0.94 + (T_j * -1.2*10^{-3})$$
  
 $R_{T=} 0.015 + (T_j * 6.4*10^{-3})$ 

Note:  $T_i$  = Diode Junction Temperature In Degrees Celsius

### **Recommended Solder Pad Layout**

Primary dimensions shown in mm. Learn more about recommended soldering profiles in this application note.



### **Product Ordering Information**

Order Number	Packing Type
C3D02060A	Tube

Learn more about power device packing & shipment information in this application note.

### **Revision History**

Document Version	Date of Release	Description of Changes
1	October-2016	Initial Release
8	March-2023	Update Package Drawing Update Landing Pad

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